

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

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| Title of Invention | Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking |
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Application Number : 10/050507



Confirmation Number: 7687

First Named Applicant: Teck Lee

Attorney Docket Number: MTI-31607

Art Unit: 2813

Examiner: Jack SJ Chen

Search string: (6308525 or 5468995 or 6610559).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

| init | Cite.No. | Patent No. | Date | Patentee | Kind | Class | Subclass |
|------|----------|------------|------------|--------------|------|-------|----------|
| | 1 | 6308525 | 2001-03-27 | Imasu et al. | | 361 | 783 |
| | 2 | 5468995 | 1995-11-21 | Higgins III | | 257 | 697 |
| | 3 | 6610559 | 2003-08-26 | Wang et al. | | 438 | 108 |

Signature

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|---------------|------|
| Examiner Name | Date |
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